

BDB Series Standard Profile DIP Switches

NEW

DIP



Features/Benefits

- Traditional full profile DIP switch
- Extended actuator for easy actuation
- Special sealed construction allows for solder washing without the need for tape seal
- RoHS compliant
- New generation price competitive

Typical Applications

- Address switch for industrial controls
- Logic switching for computers and peripherals
- Function controlling for numerous applications

Specifications

SWITCH FUNCTION: SPST - 2 thru 12 position available (except 11 position).

CONTACT RATING:

Carry: 100 mA max. @ 50 V DC.

Switch: 100 mA max. @ 5 V DC or 25 mA max. @ 25 V DC.

MECHANICAL AND ELECTRICAL LIFE: 10,000 make-and-break cycles at full load, each circuit.

CONTACT RESISTANCE: Below 50 milliohms typ. initial @ 2-4 V DC 100mA.

INSULATION RESISTANCE: 10⁹ ohms min.

DIELECTRIC STRENGTH: 300 V RMS min. @ sea level between adjacent terminals.

CAPACITANCE: 5pF max. between adjacent terminals.

STORAGE & OPERATING TEMPERATURE: -40°C to 85°C.

SHOCK: Withstands 20g 11 ms sawtooth waveform with no contact opening greater than 10 microseconds.

VIBRATION: No contact opening greater than 10 microseconds and no contact closure when exposed to vibration .06 in DA or 5g, whichever is less, from 10 to 55 Hz, and 10g from 55 to 500 Hz.

SOLDERABILITY: Per MIL-STD-202F method 208D, or EIA RS-186E method 9 (1 hour steam aging).

PACKAGING: Switches supplied in rigid dispensing tubes in full-tube quantities only: this may effect order quantity. Number of switches per tube varies with model. Switch position 1 denotes pin number 1. All switch actuators in 'OFF' position, standard.
2. Option for "ON" is available on volume demand.

Materials

HOUSING: PA46, color red (UL94V-0)

COVER: Glass filed polyester (PBT) (UL94V-0)

ACTUATOR: Glass filed polyester (PBT) (UL94V-0)

CONTACTS: Gold plate phosphor bronze

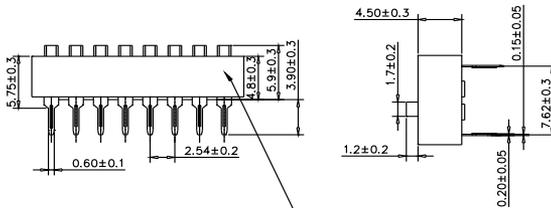
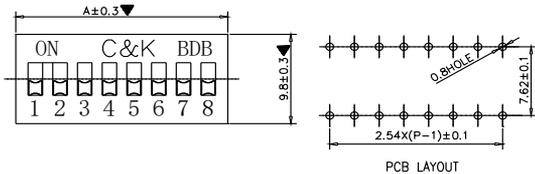
TERMINALS: Gold plate over nickel plated brass

Note: Specifications and materials listed above are for switches with standard options. For information on specific and custom switches, consult Customer Service Center.

Vertical Full Profile DIP



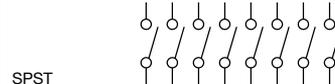
BDB08



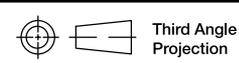
DATE CODE: YEAR+WEEK
YEAR: The letter «A» means 2009, «B» means 2010, ..., «J» means 2018, and so on
WEEK: «01» means the first week «01» means the second week, and so on

PART NUMBER	NO.POS.	DIM. 'A'	DIM. 'B'	QUANTITY PER TUBE
BDB02	2	.280 (7,11)	.100 (2,54)	70
BDB03	3	.380 (9,65)	.200 (5,08)	51
BDB04	4	.480 (12,19)	.300 (7,62)	40
BDB05	5	.580 (14,73)	.400 (10,16)	33
BDB06	6	.680 (17,27)	.500 (12,75)	28
BDB07	7	.780 (19,81)	.600 (15,24)	24
BDB08	8	.880 (22,35)	.700 (17,78)	21
BDB09	9	.980 (24,89)	.800 (20,32)	19
BDB10	10	1.080 (27,43)	.900 (22,86)	17
BDB12	12	1.280 (32,51)	1.100 (27,94)	14

Schematic



SPST



Third Angle Projection

Dimensions are shown: Inch (mm)
Specifications and dimensions subject to change



21 aug 2018

NEW

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DIP

Installation, Soldering and Cleaning

All BDB Series Standard Profile DIP Switches can be hand soldered or machine soldered without the use of boot, caps, tapes or special attention. Open base washable models have unique design, allowing solvent cleaners and water/detergent solutions to flush and clean the electrical contacts of the contaminants and fluxes. For best results, follow these directions:

- 1) Wave soldering recommended at 500° F (260°C) solder temperature.
- 2) Hand solder using 30 watt small tip iron controlled at 500° F (260°C), 10 seconds max./terminal.
- 3) Open base washable models: Clean flux using forced rinse, high agitation or triple bath cleaning method.
DO NOT mask or cover switch in any way during cleaning. Switch is designed for easy solvent flush out.
- 4) All switch actuators must be in 'OFF' position during soldering and cleaning processes.



Third Angle
Projection

Dimensions are shown: Inch (mm)
Specifications and dimensions subject to change